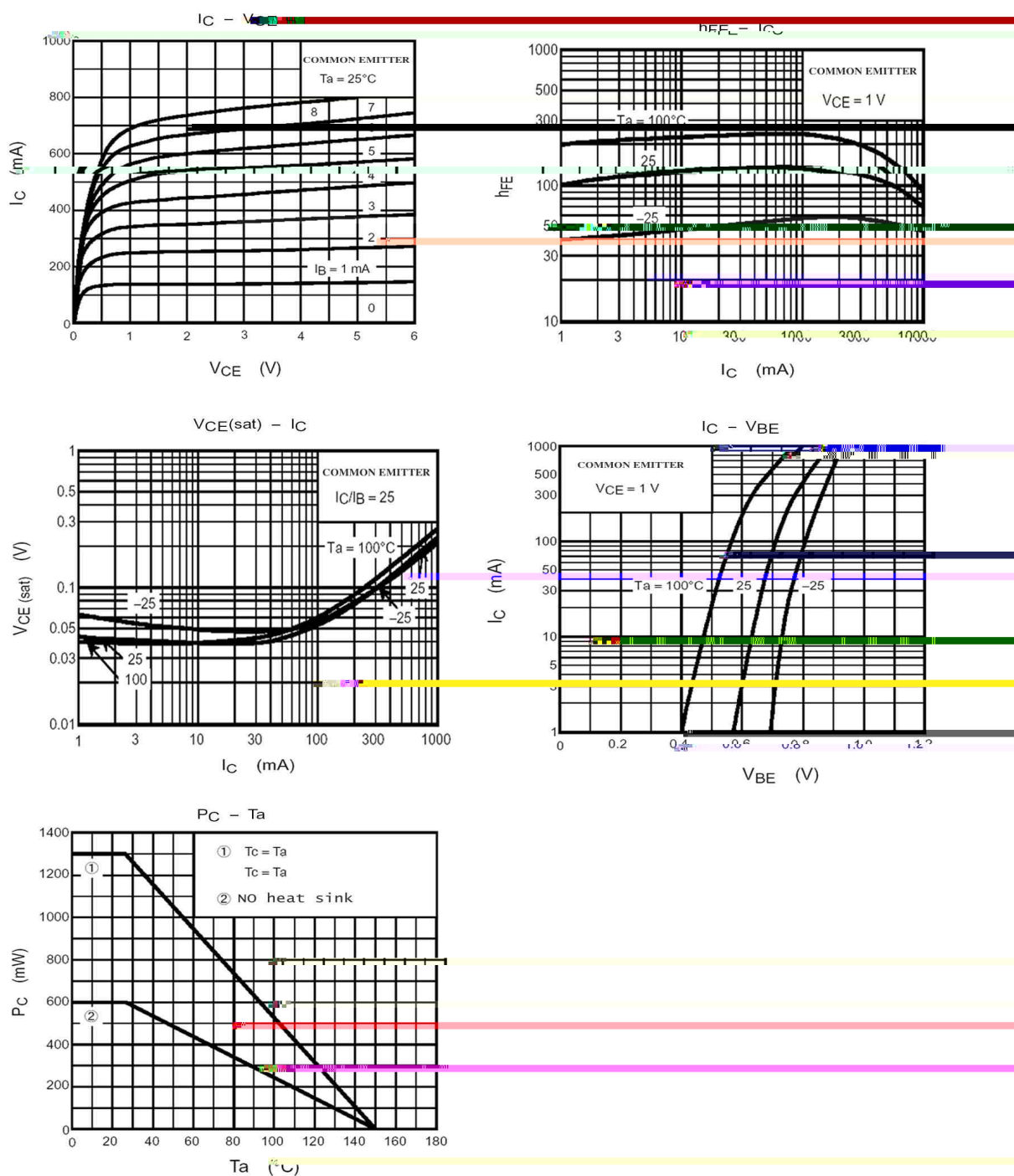


Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	35	V
Collector to Emitter Voltage	V_{CEO}	30	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	800	mA
Emitter Current - Continuous	I_E	-800	mA
Collector Power Dissipation	P_C	600	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=10mA$ $I_E=0$	30			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=35V$ $I_E=0$			0.1	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=5.0V$ $I_C=0$			0.1	μA
DC Current Gain	$h_{FE(1)}$	$V_{CE}=1.0V$ $I_C=100mA$	100		320	
	$h_{FE(2)}$	$V_{CE}=1.0V$ $I_C=700mA$	35			

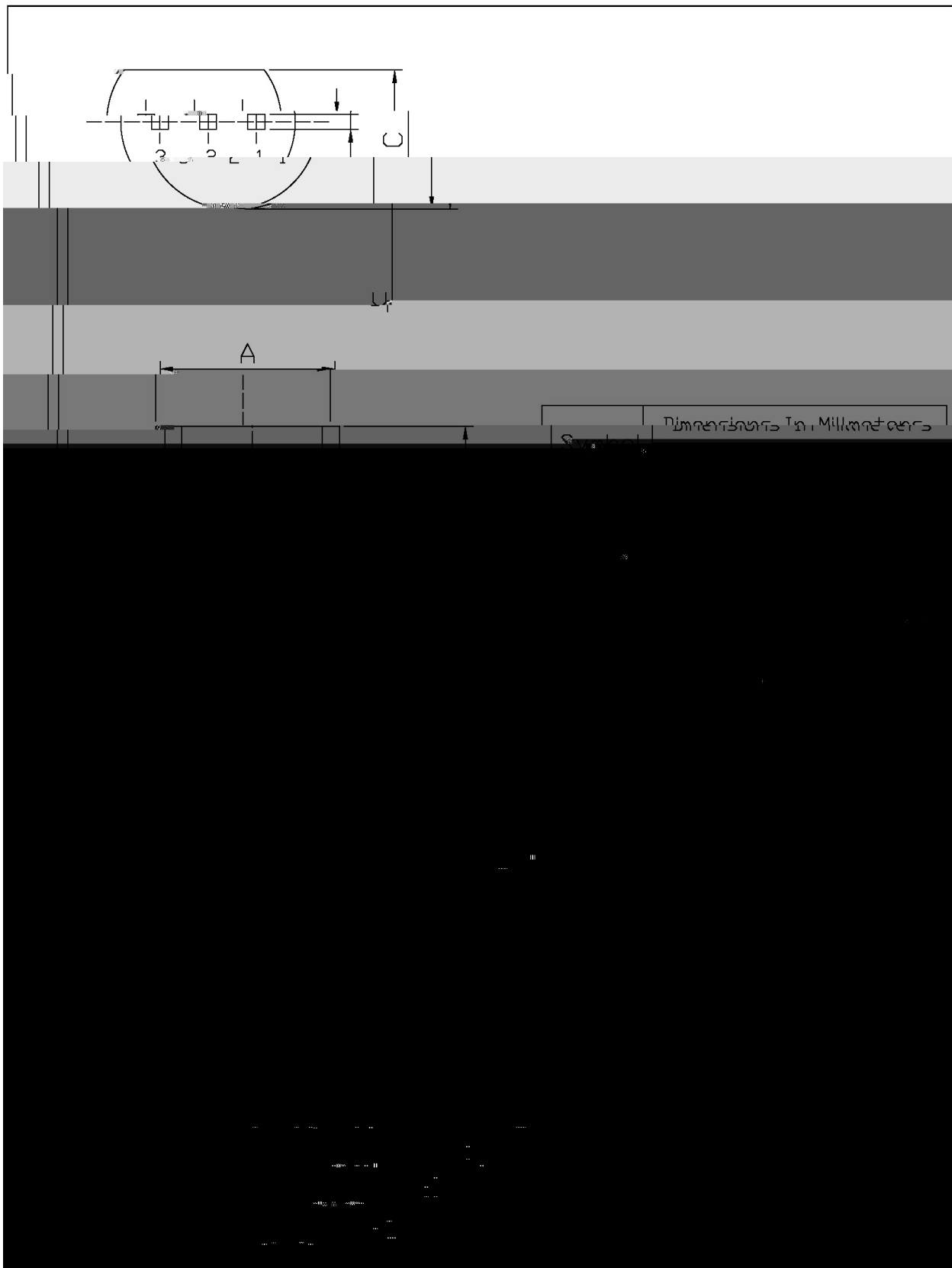
/ Electrical Characteristic Curve

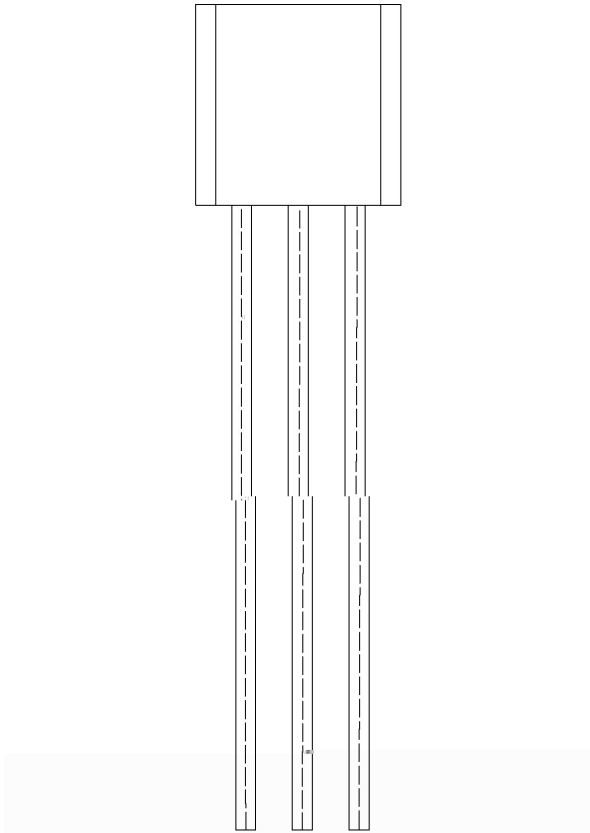


/ Package Dimensions

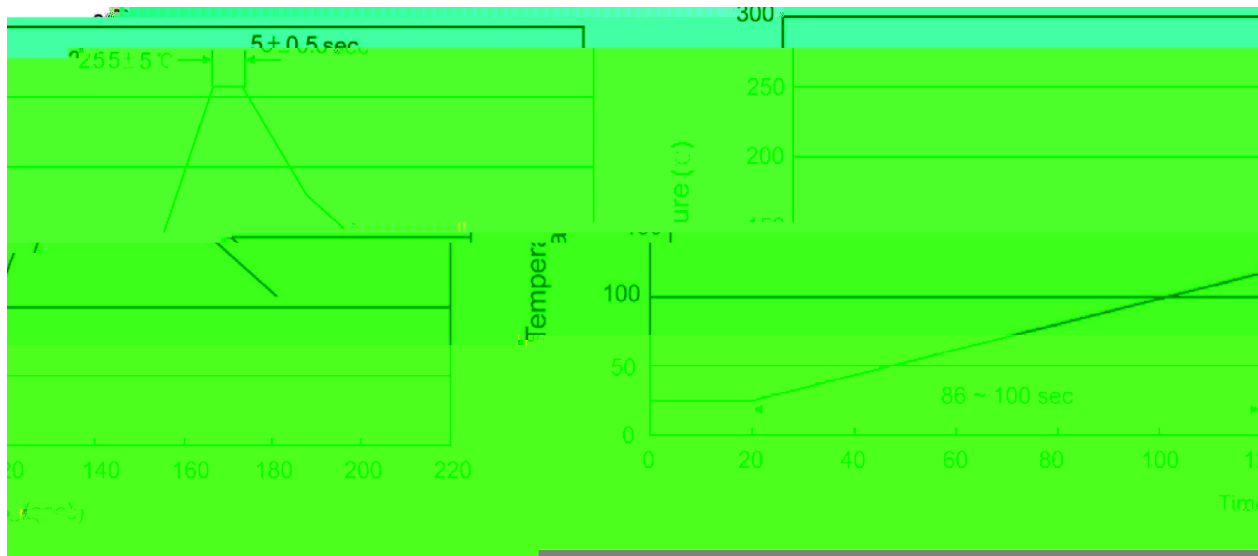
TO-92

Unit: mm





() / Temperature Profile for Dip Soldering(Pb-Free)



注意

1. 预加热: 25~150℃, 时间: 60~90sec;
2. 峰值温度: 255±5℃, 持续时间: 5±0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

1. Preheating: 25~150℃, Time: 60~90sec.
2. Peak Temp.: 255±5℃, Duration: 5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度: 270±5℃, 时间: 10±1 sec. Temp: 270±5 Time: 10±1 sec

/ Packaging SPEC.

包装形式 / BULK

Package Type	Units	Dimension	(unit: mm ³)
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